

Features

- ★ Split Gate Trench MOSFET technology
- ★ Excellent package for heat dissipation
- ★ High density cell design for low RDS(ON)

Product Summary

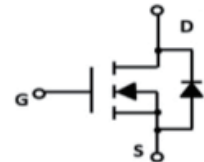
RoHS

BVDSS	RDS(ON)	ID
120V	6mΩ	125A

Description

- ★ DC-DC Converters
- ★ Power management functions
- ★ Synchronous-rectification applications

TO-220AB Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-to-Source Voltage	120	V
V <sub>GS</sub>	Gate-to-Source Voltage	±20	V
I <sub>D</sub>	Continuous Drain Current	T <sub>C</sub> = 25°C	125
		T <sub>C</sub> = 100°C	80
I <sub>DM</sub>	Pulsed Drain Current <sup>(1)</sup>	320	A
E <sub>AS</sub>	Single Pulsed Avalanche Energy <sup>(2)</sup>	326	mJ
P <sub>D</sub>	Power Dissipation	T <sub>C</sub> = 25°C	119
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient <sup>(3)</sup>	52	°C/W
R <sub>θJC</sub>	Thermal Resistance, Junction to Case	1.05	
T <sub>J</sub> , T <sub>STG</sub>	Junction & Storage Temperature Range	-55 to 150	°C
T <sub>I</sub>	Maximum Temperature for Soldering	260	°C

Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D = -250\mu A$	120	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -30V, V_{GS}=0V,$	-	-	1	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D = -250\mu A$	2.5	3	3.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance	$V_{GS} = 10V, I_D = 20A$	-	6	7.5	m $\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=60V, V_{GS}=0V, f=1.0MHz$	-	3614	-	pF
$C_{oss}$	Output Capacitance		-	423	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	12	-	pF
$R_g$	Gate Resistance		-	0.84	-	$\Omega$
<b>Resistive Switching Characteristics</b>						
$Q_g$	Total Gate Charge	$V_{DS} = 60V, I_D = 20A,$ $V_{GS} = 0 \sim 10V$	-	60.8	-	nC
$Q_{gs}$	Gate-Source Charge		-	18.8	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	14.7	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DS} = 60V, I_D = 20A,$ $V_{GS} = 10V R_G = 5\Omega$	-	20	-	ns
$t_r$	Turn-on Rise Time		-	65	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	32	-	ns
$t_f$	Turn-off Fall Time		-	49	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	95	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S = 20A$	-	0.83	1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time	$I_S=40A, dI/dt=100A/\mu s$	-	60	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	109	-	nC

## Notes:

1. Repetitive rating; pulse width limited by maximum junction temperature

2.  $V_{DD}=60V, L=0.5mH, R_g=25\Omega, \text{Starting } T_J=25^\circ\text{C}$

Typical Electrical and Thermal Characteristics (Curves)

Figure 1: Typ. output characteristics

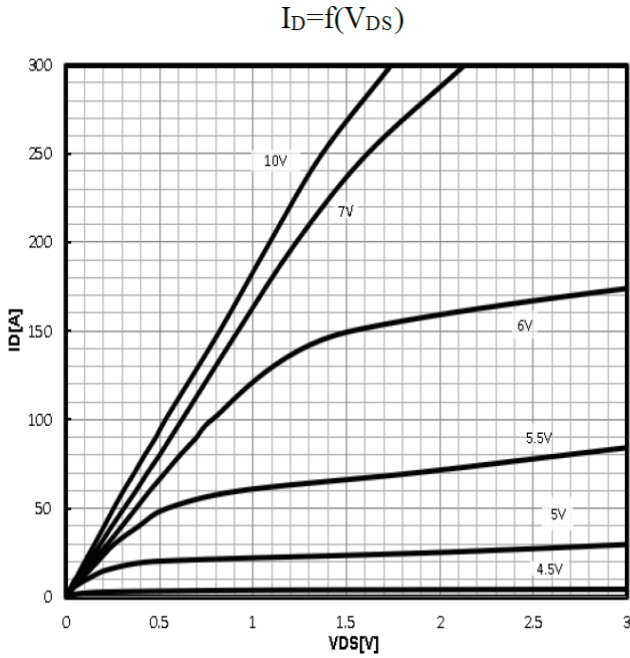


Figure 2: Typ. drain-source on resistance

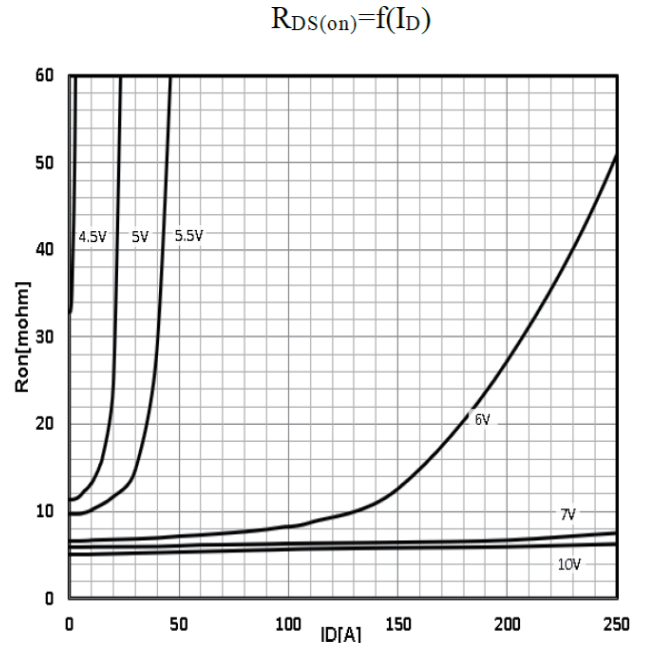


Figure 3: Typ. transfer characteristics

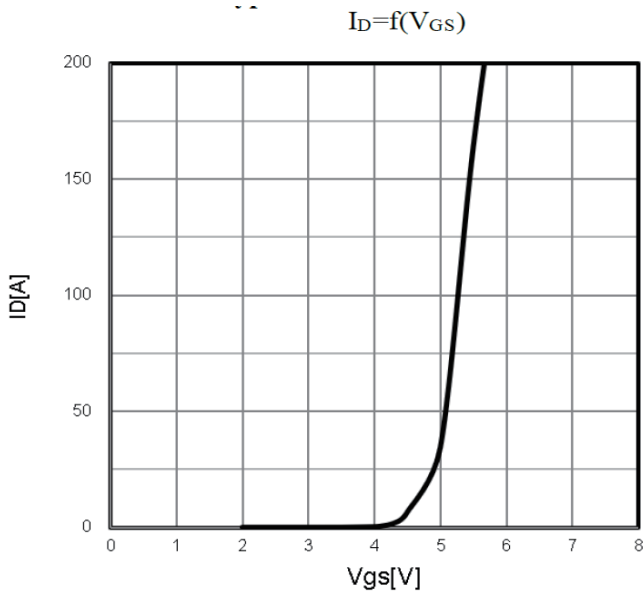
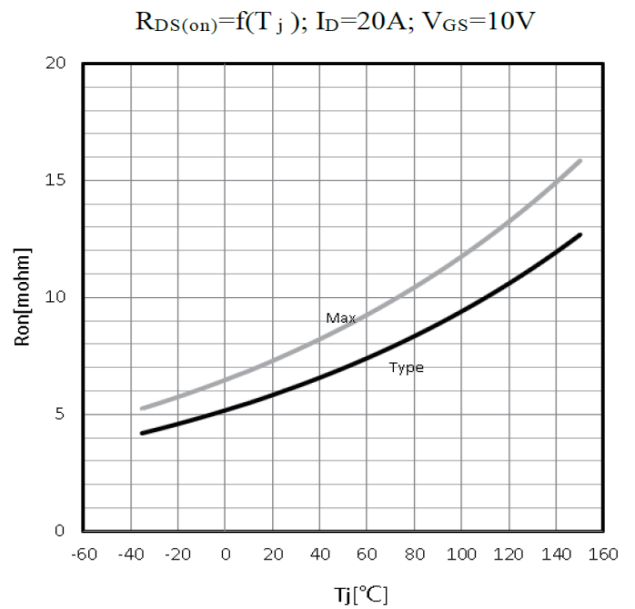


Figure 4: Drain-source on-state resistance



Typical Performance Characteristics

Figure 5: Gate Threshold Voltage

$$V_{TH} = f(T_j); I_D = 250\mu A$$

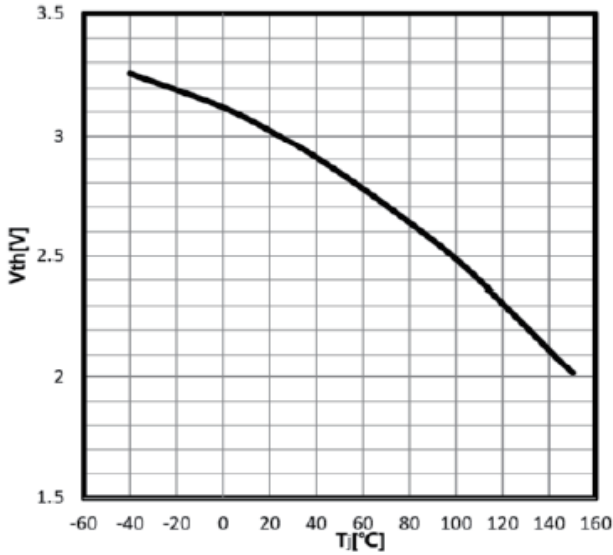


Figure 6: Drain-source breakdown voltage

$$V_{BR(DSS)} = f(T_j); I_D = 250\mu A$$

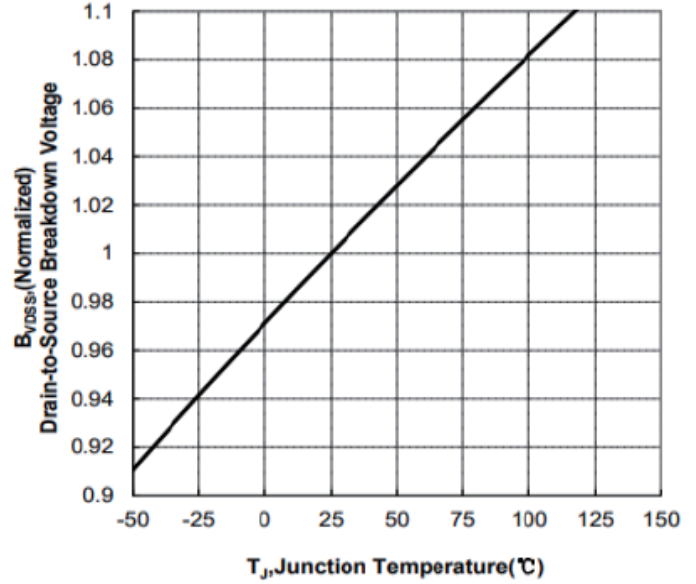


Figure 7: Typ. gate charge

$$\bar{V}_{GS} = f(Q_{gate})$$

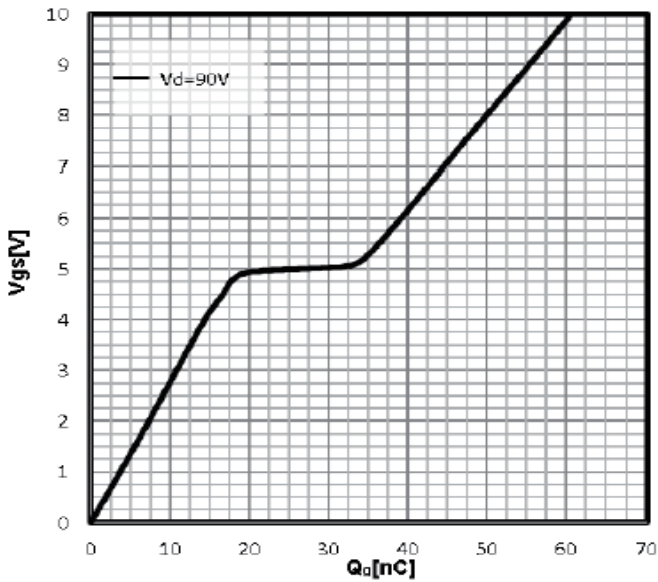
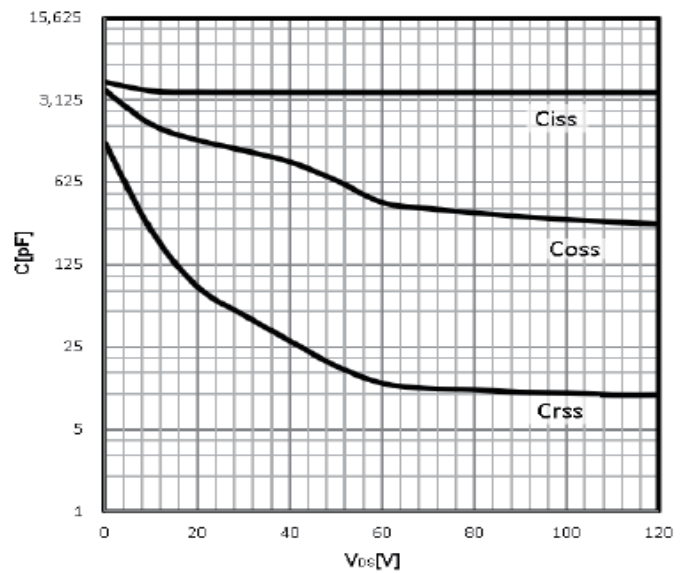


Figure 8: Typ. capacitances

$$C = f(\bar{V}_{DS}); \bar{V}_{GS} = 0V; f = 1MHz$$



Typical Performance Characteristics

Figure 9: Power Dissipation

$$P_{tot} = f(T_j)$$

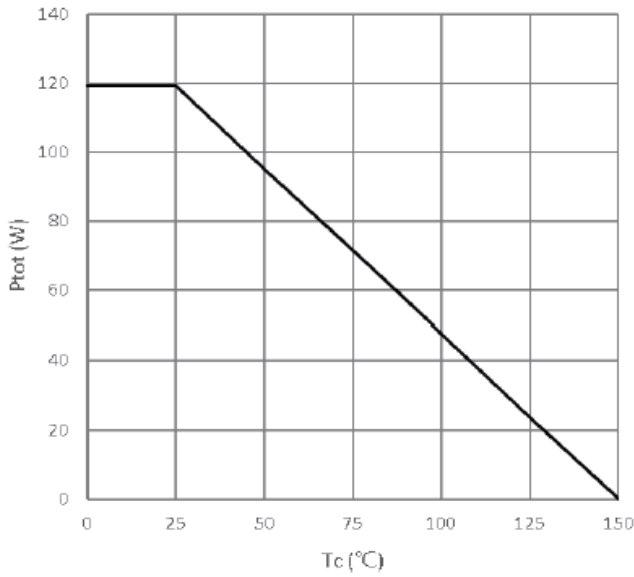


Figure 10: Maximum Drain Current

$$I_D = f(T_c)$$

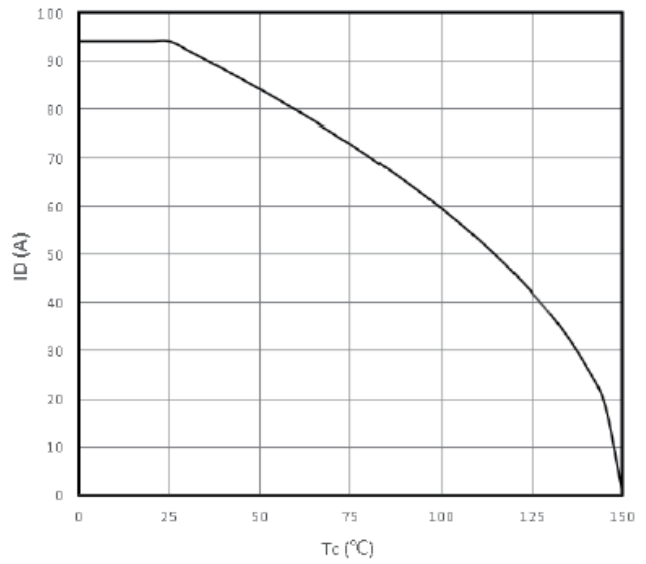


Figure 11: Safe operating area

$$I_D = f(V_{DS})$$

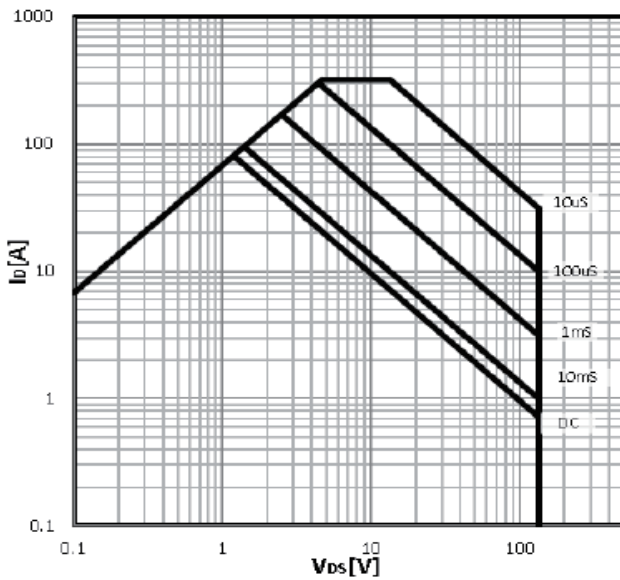
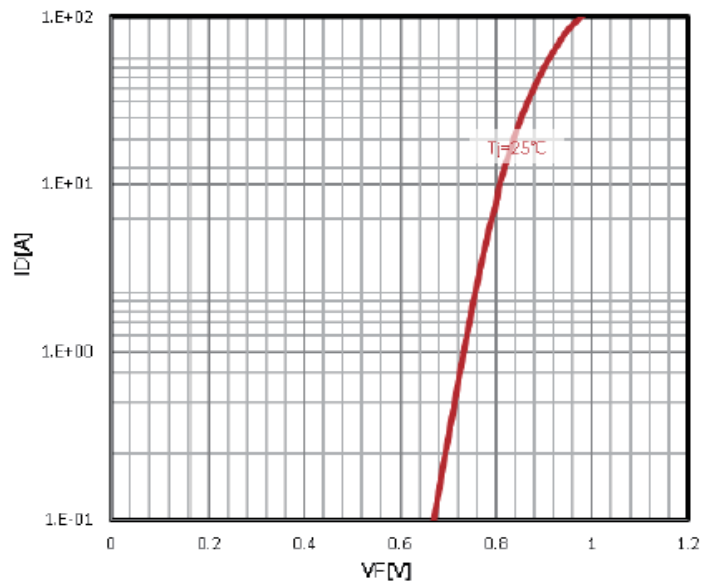


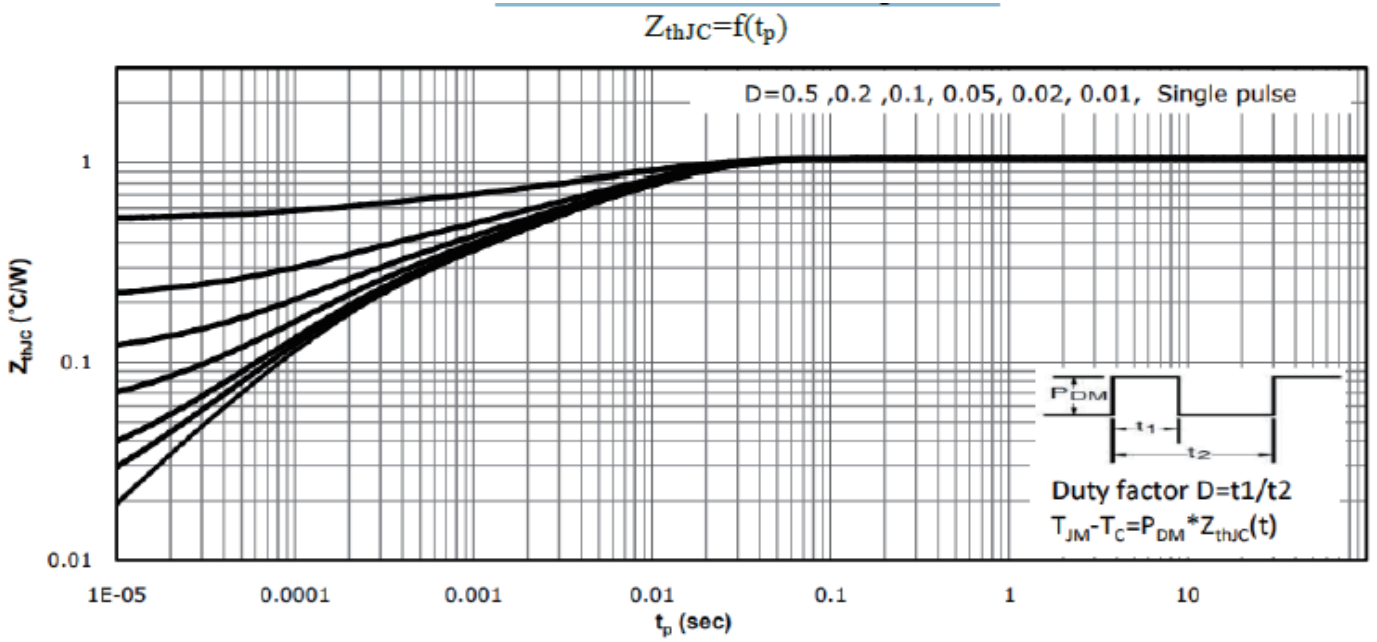
Figure 12: Body Diode Forward Voltage

$$I_F = f(V_{GS})$$

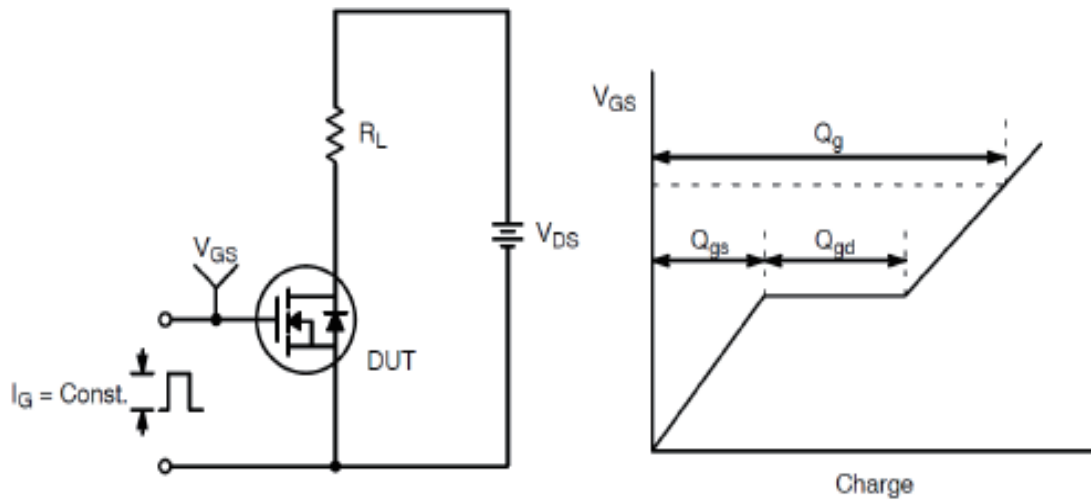


Typical Performance Characteristics

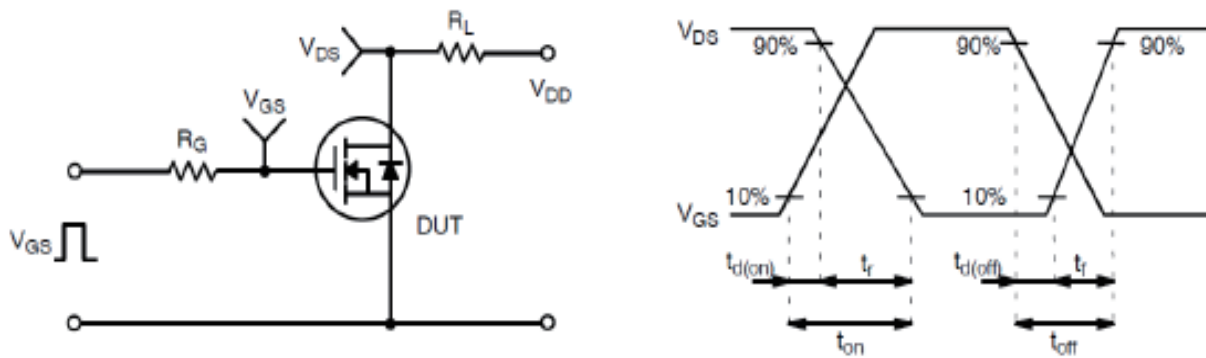
Figure 7: Max. transient thermal impedance



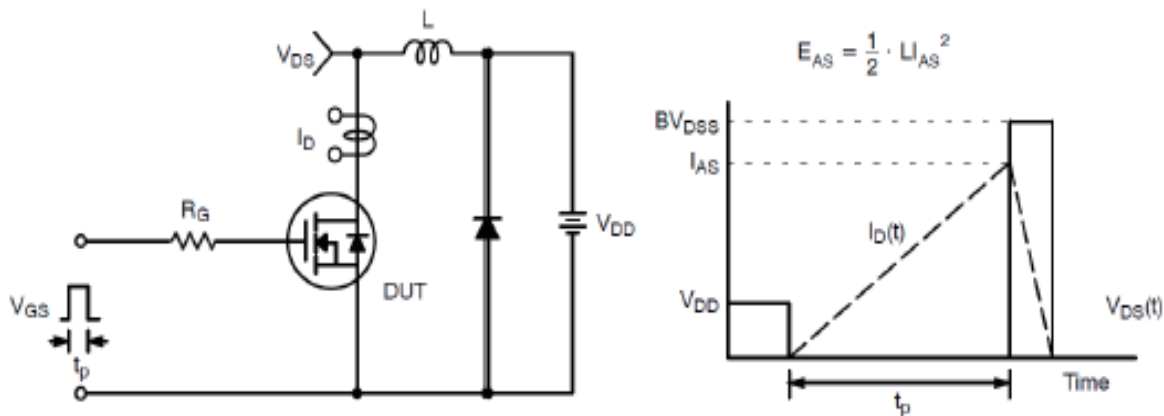
Test Circuit and Waveform:



Gate Charge Test Circuit & Waveform

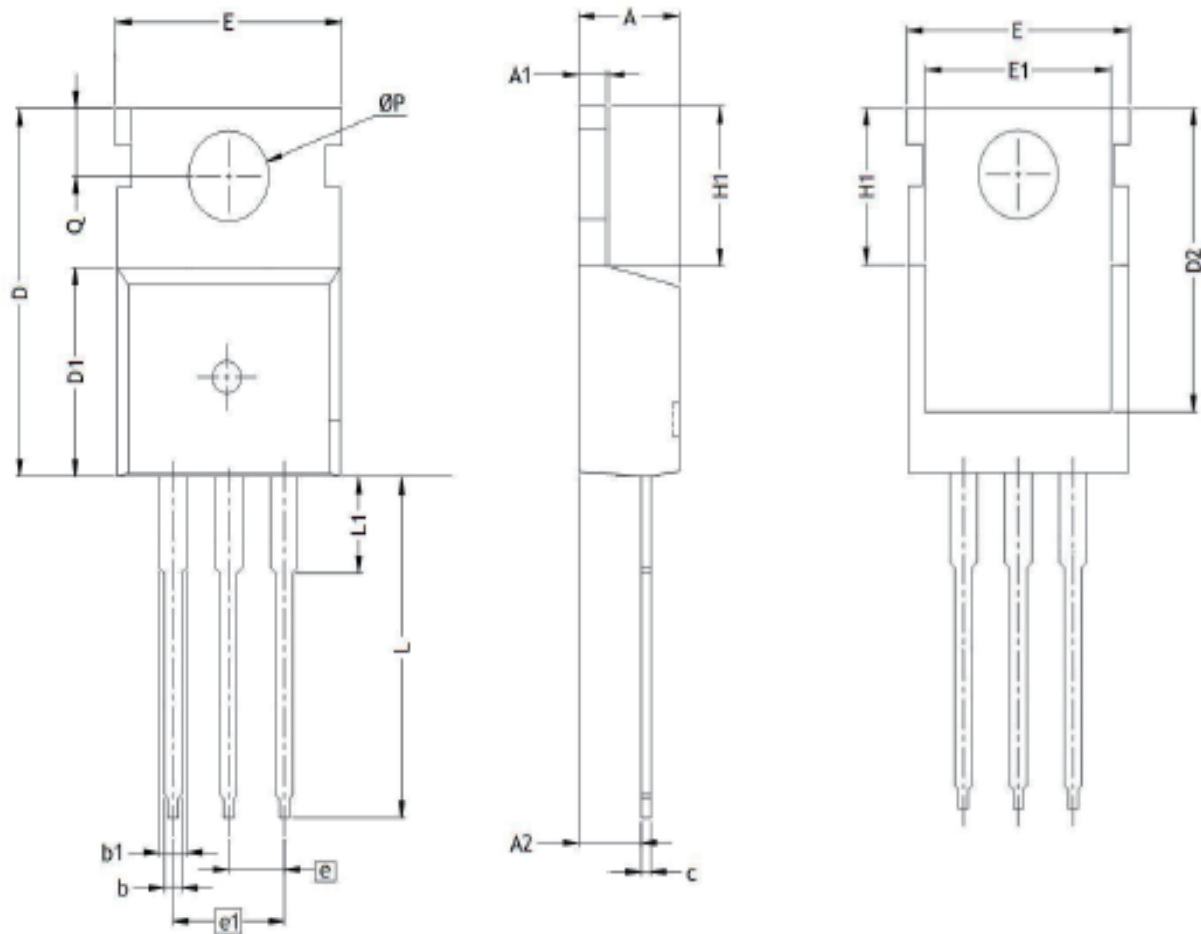


Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

Mechanical Dimensions for TO-220AB



UNIT: mm

SYMBOLS	A	A1	A2	b	b1	c	D	D1	D2	E	E1	e
MIN	4.25	1.25	2.35	0.7	1.15	0.45	14.35	8.80	13.05	9.90	7.85	2.540
MAX	4.65	1.35	2.55	0.9	1.75	0.60	15.95	9.50	13.65	10.35	8.85	BSC
SYMBOLS	e1	H1	L	L1	Q	$\phi P$						
MIN	5.080	6.30	12.85	2.85	2.70	3.50						
MAX	BSC	6.65	13.50	3.25	2.90	3.70						



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